

Form PTO-1449 (modified)  
List of Patent and Publications For  
Applicant's Information Disclosure  
Statement  
(use several sheets if necessary)

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Applicant:  
IWA0 NOZAWA ET AL

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Art Unit:  
1753 1742

### U.S. PATENT DOCUMENTS

Exr's Initial		Document No.							Date	Name	Class	Sub class	Filing Date
✓ 2	AA	6	3	3	3	4	8	8	3/7/2000	An et al	148	24	10/30/97
✓ 2	AB	0	3	0	7	1	6	0	10/23/01	Mei et al	174	256	10/29/98
	AC												
	AD												
	AE												

### FOREIGN PATENT DOCUMENTS

		Document No.							Date	Country	Class	Sub class	Translation	
													Yes	No
✓ 2	AF	0	6	5	2	0	7	2	5/10/95	EP				
	AG													
	AH													

### OTHER ART (Including author, title, date pertinent pages, etc.)

✓ 2	AI	Shi-Wei Ricky Lee et al, "Assessment on the Effects of Electronless Nickel Plating on the Reliability of Solder Ball Attachment to the Bond Pads of PBGA Substrate", 2000 Proceedings, 50th Electronic Components and Technology Conference, ECTC 2000, Las Vegas, May 21 - 24, 2000. Proceedings of the Electronic Components and Technology Conference, New York; IEEE US, vol. Conf. 50, May 21, 2000, pages 868 - 873											
✓	AJ	Zequn Mei et al, "Brittle Interfacial Fracture of PBGA Packages Soldered on Electroless Nickel/Immersion Gold", Electronic Components & Technology Conference, 1998, 48th IEEE Seattle, Wa. May 25 - 28, 1998, New York, IEEE, US May 25, 1998, pages 952 - 961											
✓	AK	Patent Abstracts of Japan, vol. 1999, No. 04, April 30, 1999, Abstract of JP 11-00791 A, published on 1/6/99											
✓	AL	Patent Abstracts of Japan, vol. 1995, no. 11, December 26, 1995, Abstract of JP 07-195189 A, published on 8/1/95											
✓ 2	AM	Patent Abstracts of Japan, vol. 2000, no. 13, February 5, 2001, Abstract of JP 2000-277895 A, published on 10/6/2000											

Examiner

S. I.

Date considered:

3/18/06

EXAMINER: Initial if reference considered, no matter whether citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.